

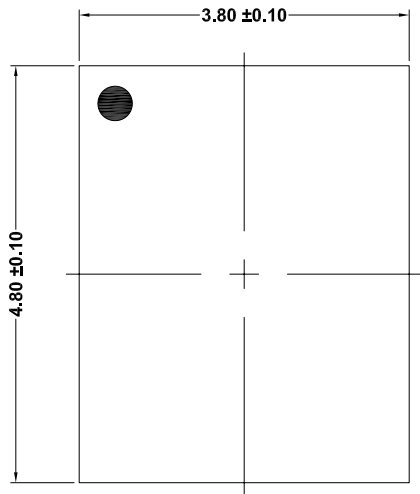
Plastic Packages for Integrated Circuits

Package Outline Drawing

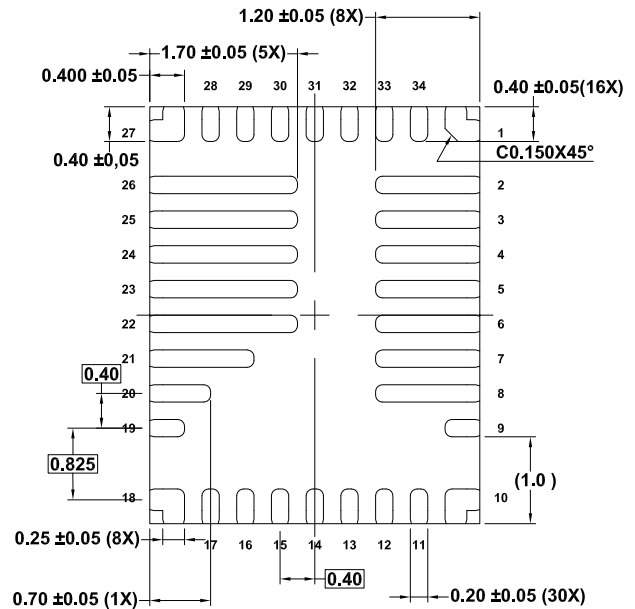
L34.3.8x4.8

34 Lead Flip Chip Quad Flat No-Lead Package (FCQFN)

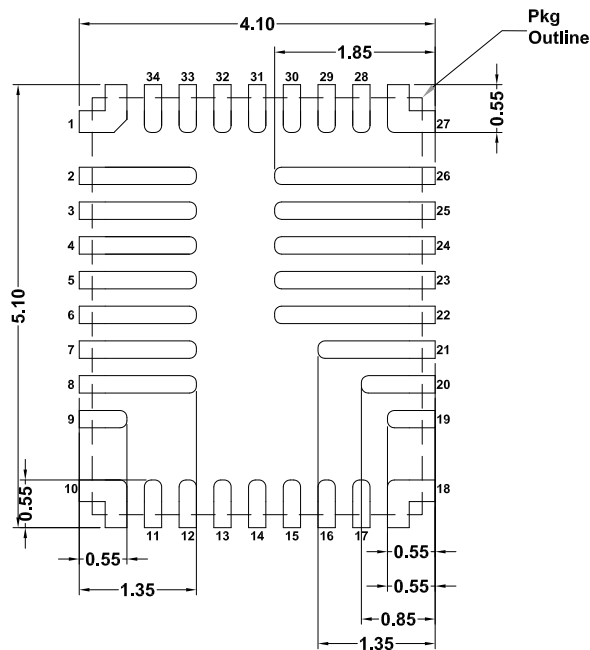
Rev 0, 11/2021



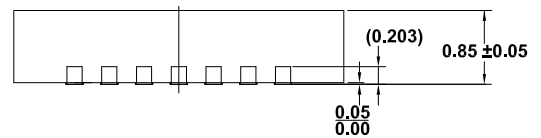
Top View



Bottom View



Typical Recommended Land Pattern



Side View

Notes:

1. Dimensioning and tolerancing conforms to ASME Y14.5M - 1994.
2. All dimensions are in millimeters, Dimensions in () for reference only.